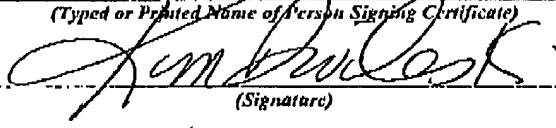


<b>CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8)</b>			<b>Docket No.</b> END920010135US2
Applicant(s): <u>Alcoe et al.</u>			
Application No. 10/665,669	Filing Date 9/18/2003	Examiner Thao, X. Le	Group Art Unit 2814
Invention: <u>THERMALLY ENHANCED LID FOR MULTI-CHIP MODULES</u>			
<b>RECEIVED</b> <b>CENTRAL FAX CENTER</b> <b>MAY 17 2005</b>			
I hereby certify that this <u>Request for Reconsideration (12 pages)</u> (Identify type of correspondence)			
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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Appl. No.: 10/665,669

Applicant(s): Alcoe et al.

Filed.: September 18, 2003

Art Unit: 2814

Dkt. No.: END920010135US2

Examiner: Le, Thao X.

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**MAY 17 2005****Title: THERMALLY ENHANCED LID FOR MULTI-CHIP MODULES**

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Honorable Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

**REQUEST FOR RECONSIDERATION**

This Request for Reconsideration is being filed in response to the Final Office Action mailed on March 23, 2005. Applicants request this Amendment be entered in the above-identified application and reconsideration of the application in view of the Amendments and Remarks that follow.